

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT7292334

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
CHING-HUANG LU	01/23/2013
SIMON SIU-SING CHAN	01/23/2013
HIDEHIKO SHIRAIWA	01/23/2013
LEI XUE	01/23/2013
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SPANSION LLC
<b>Street Address:</b>	915 DEGUIGNE DRIVE
<b>City:</b>	SUNNYVALE
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	94088
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Patent Number:	11183509
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(408)545-6911
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	4085456934
<b>Email:</b>	patents@cypress.com, sheena.hicks-EE@infineon.com
<b>Correspondent Name:</b>	CYPRESS SEMICONDUCTOR CORPORATION
<b>Address Line 1:</b>	198 CHAMPION COURT
<b>Address Line 4:</b>	SAN JOSE, CALIFORNIA 95134-1709
<b>ATTORNEY DOCKET NUMBER:</b>	SPN13007D1C3
<b>NAME OF SUBMITTER:</b>	KIN HUNG LAI
<b>SIGNATURE:</b>	/Kin Hung Lai/
<b>DATE SIGNED:</b>	04/21/2022
<b>Total Attachments: 2</b>	
source=SPN13007D1C3_parentAssignment_Spansion_04212022#page1.tif	
source=SPN13007D1C3_parentAssignment_Spansion_04212022#page2.tif	

### ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) or equivalent and other good and valuable consideration paid to each of the undersigned inventors: **(1) Ching-Huang LU, (2) Simon Siu-Sing CHAN, (3) Hidehiko SHIRAIWA and (4) Lei XUE**, hereby sell and assign to **Spansion LLC**, a corporation formed under the laws of Delaware, whose mailing address is 915 DeGuigne Drive, Sunnyvale, CA 94088-3453 (hereafter referred to as the Assignee), his/her entire right, title and interest, including the right to sue for past infringement and to collect for all past, present and future damages, for the United States of America (as defined in 35 U.S.C. § 100) and throughout the world,

(a) in the invention(s) known as **Non-Volatile Memory With Silicided Bit Line Contacts** for which application(s) for patent in the United States of America has a filing date of herewith (also known as United States Application No. To be assigned), in any and all applications thereon, in any and all Letters Patent(s) therefor, and

(b) in any and all applications that claim the benefit of the patent application listed above in part (a), including non-provisional applications, continuing (continuation, divisional, or continuation-in-part) applications, reissues, extensions, renewals and reexaminations of the patent application or Letters Patent therefor listed above in part (a), to the full extent of the term or terms for which Letters Patents issue, and

(c) in any and all inventions described in the patent application listed above in part (a), and in any and all forms of intellectual and industrial property protection derivable from such patent application, and that are derivable from any and all continuing applications, reissues, extensions, renewals and reexaminations of such patent application, including, without limitation, patents, applications, utility models, inventor's certificates, and designs together with the right to file applications therefor; and including the right to claim the same priority rights from any previously filed applications under the International Agreement for the Protection of Industrial Property, or any other international agreement, or the domestic laws of the country in which any such application is filed, as may be applicable;

all such rights, title and interest to be held and enjoyed by the above-named Assignee, its successors, legal representatives and assigns to the same extent as all such rights, title and interest would have been held and enjoyed by the Assignor had this assignment and sale not been made.

The undersigned inventors agree to execute all papers necessary in connection with the application(s) and any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue, reexamination or corresponding application(s) thereof and also to execute separate assignments in connection with such application(s) as the Assignee may deem necessary or expedient.


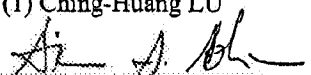

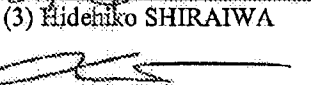
The undersigned inventors agree to execute all papers necessary in connection with any interference or patent enforcement action (judicial or otherwise) related to the application(s) or any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue or reexamination application(s) thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference or patent enforcement action.

The undersigned inventors hereby represent that he/she has full right to convey the entire interest herein assigned, and that he/she has not executed, and will not execute, any agreement in conflict therewith.

The undersigned inventors hereby grant the patent practitioners associated with **CUSTOMER NUMBER 105945** the power to insert in this assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

The undersigned inventors hereby represent that he/she understands that the patent practitioners associated with **CUSTOMER NUMBER 105945** are the legal representatives of, and attorneys for, the assignee, and are NOT the legal representatives of, and attorneys for, the inventors.

IN WITNESS WHEREOF, executed by the undersigned inventors on the date opposite his/her name.

Date: <u>01/23/2013</u>	Signature of Inventor: <u></u> (1) Ching-Huang LU
Date: <u>1/23/2013</u>	Signature of Inventor: <u></u> (2) Simon Siu-Sing CHAN
Date: <u>1/23/2013</u>	Signature of Inventor: <u></u> (3) Hidehiko SHIRAIWA
Date: <u>1/23/2013</u>	Signature of Inventor: <u></u> (4) Lei XUE

1592650\_1.DOCX